

● TO-252 Power Dissipation

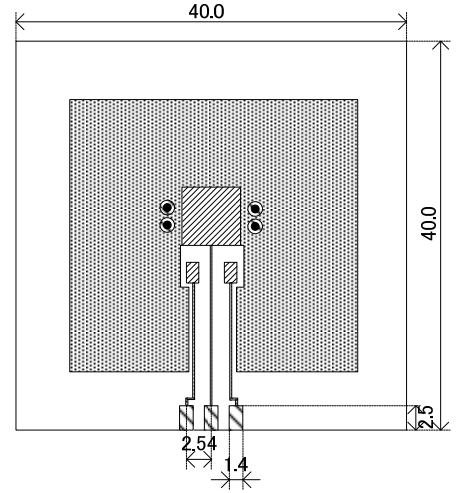
Power dissipation data for the TO-252 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as the reference data taken in the following condition.

1.Measurement Condition

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
- Material: Glass Epoxy (FR-4)



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tj max = 125°C)

| Ambient Temperature (°C) | Power Dissipation Pd (mW) | Thermal Resistance (°C/W) |
|--------------------------|---------------------------|---------------------------|
| 25 | 1800 | 55.56 |
| 85 | 720 | |

